



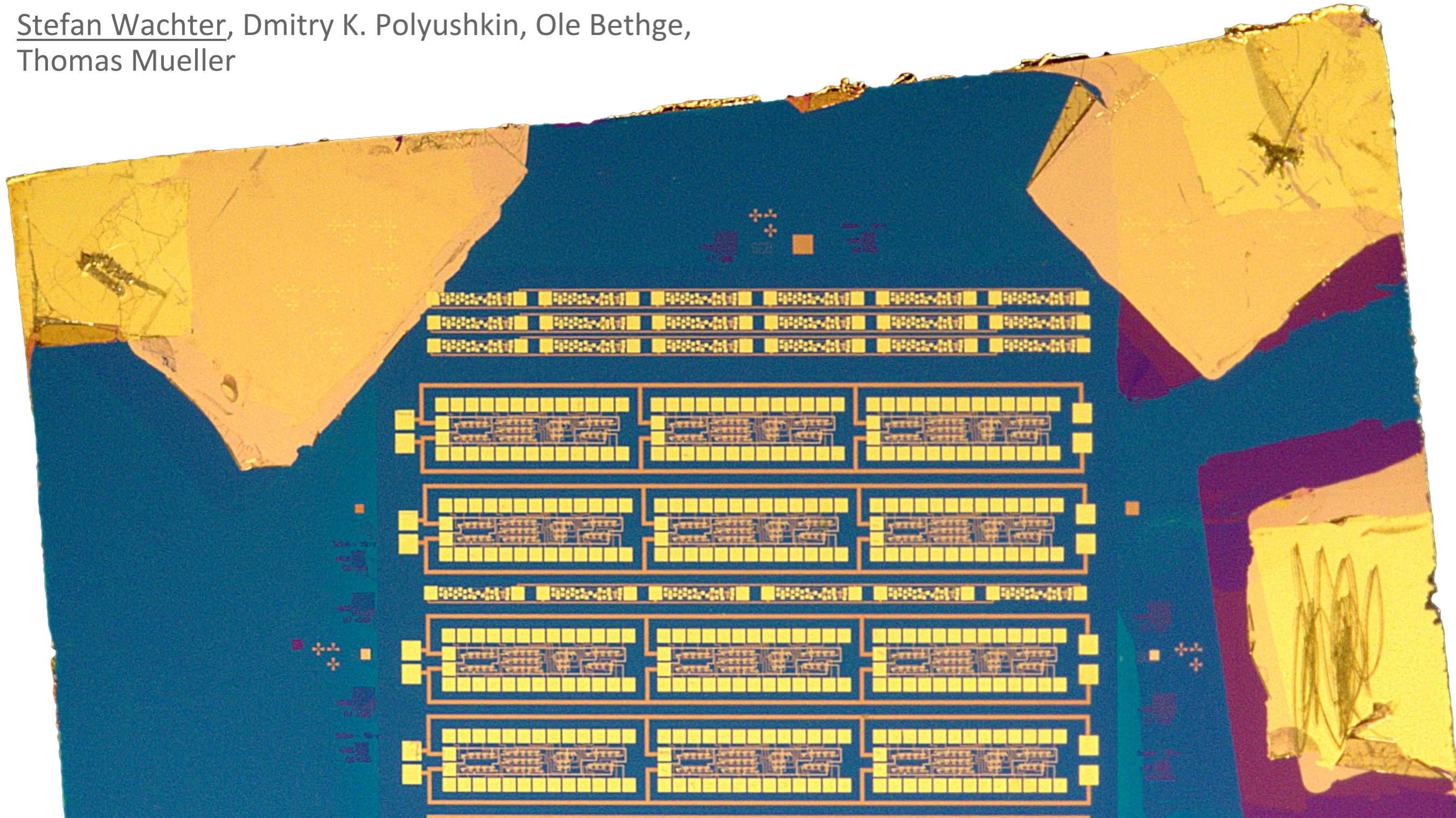
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Vienna University of Technology

FWF  
Der Wissenschaftsfonds.

 GRAPHENE FLAGSHIP

# 2D digital electronics

Stefan Wachter, Dmitry K. Polyushkin, Ole Bethge,  
Thomas Mueller



# 2D Electronics?

## **2D materials offer:**

- improved electrostatic control
- low sub-threshold slope (TFET)
- no short channel effects

## **which ultimately results in:**

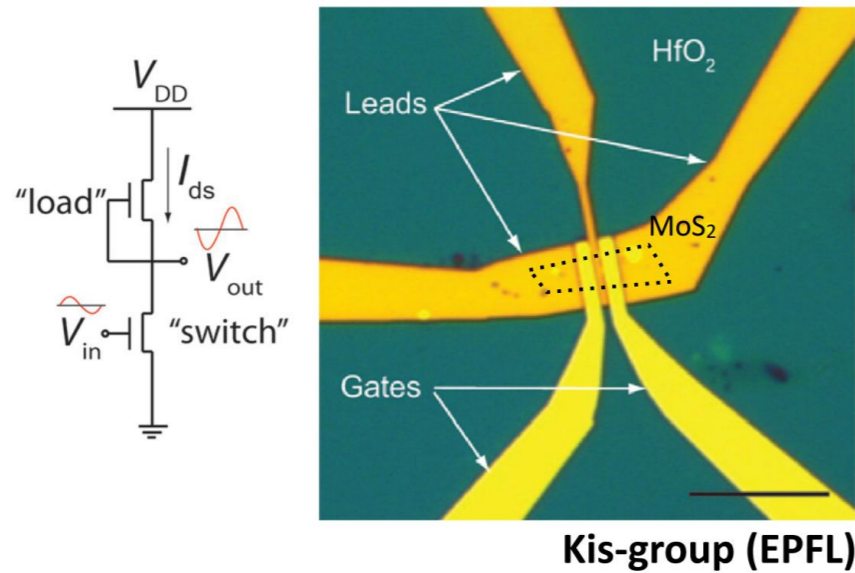
- larger integration density
- low power consumption

## **in addition:**

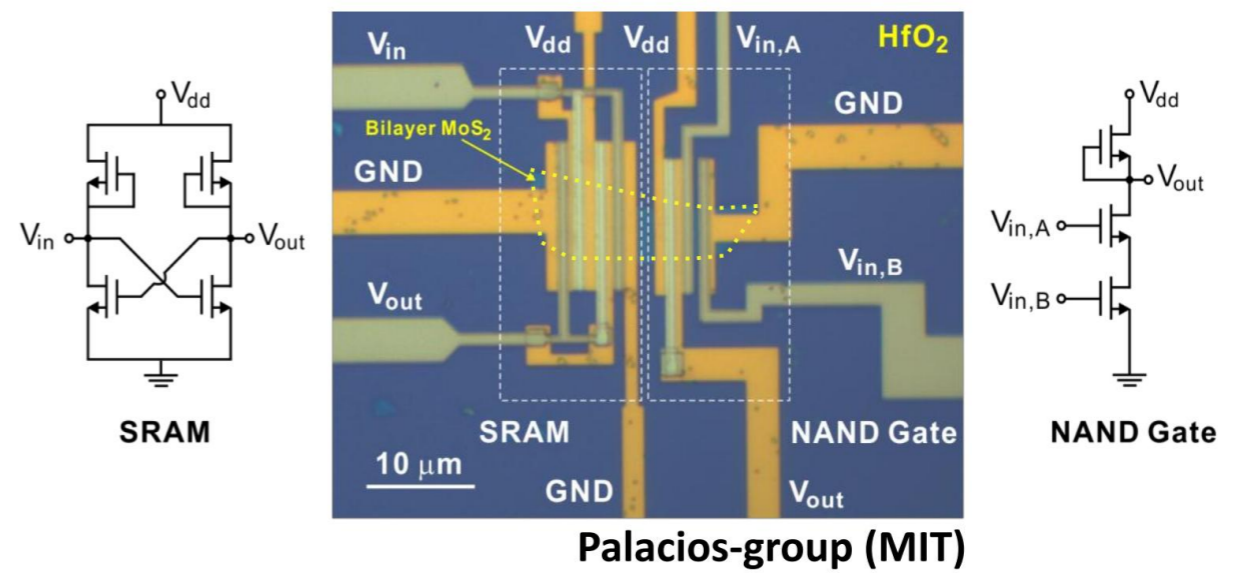
- flexible
- transparent

# Complexity of 2D semiconductor circuits

- analog circuits



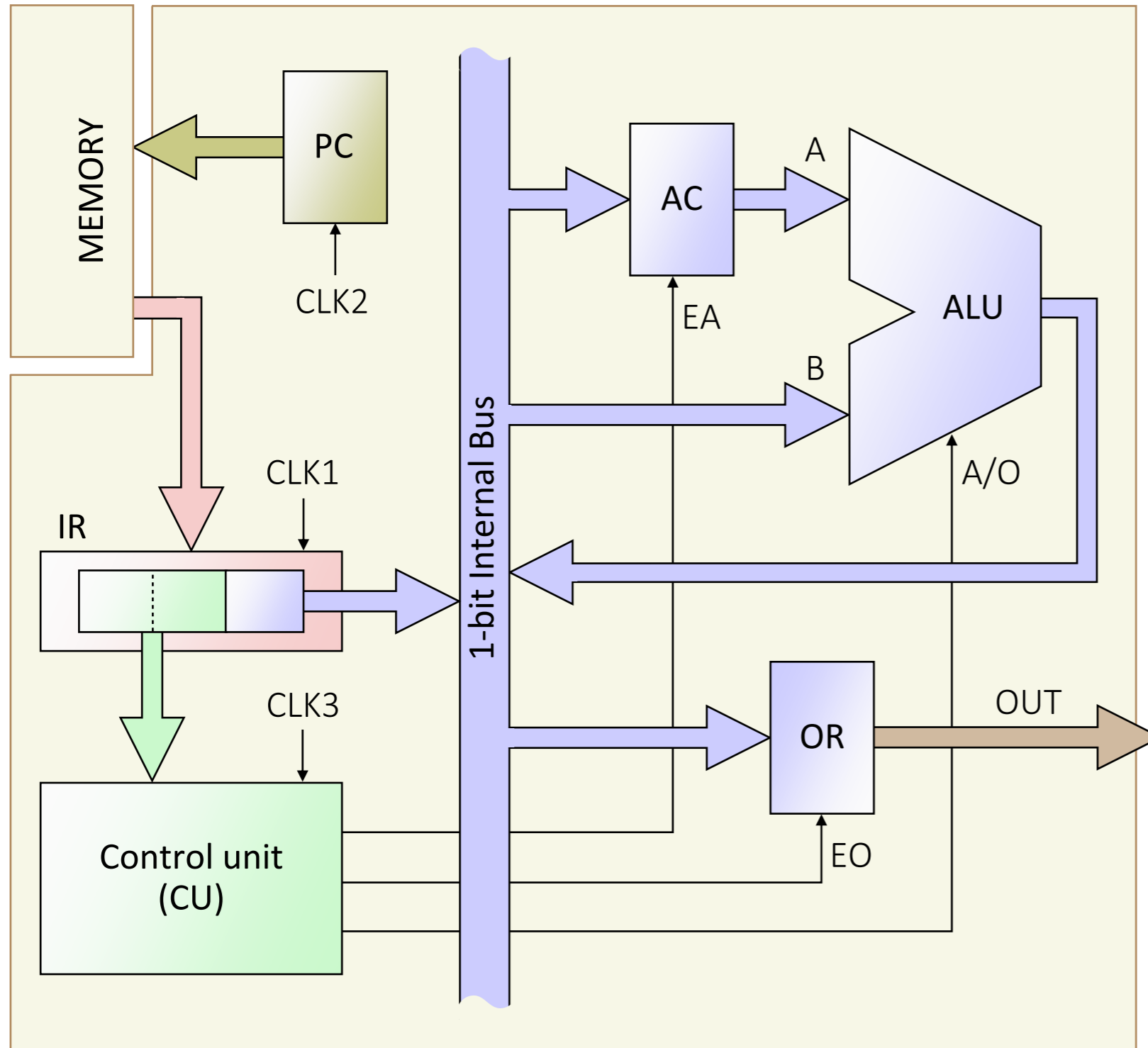
- digital circuits



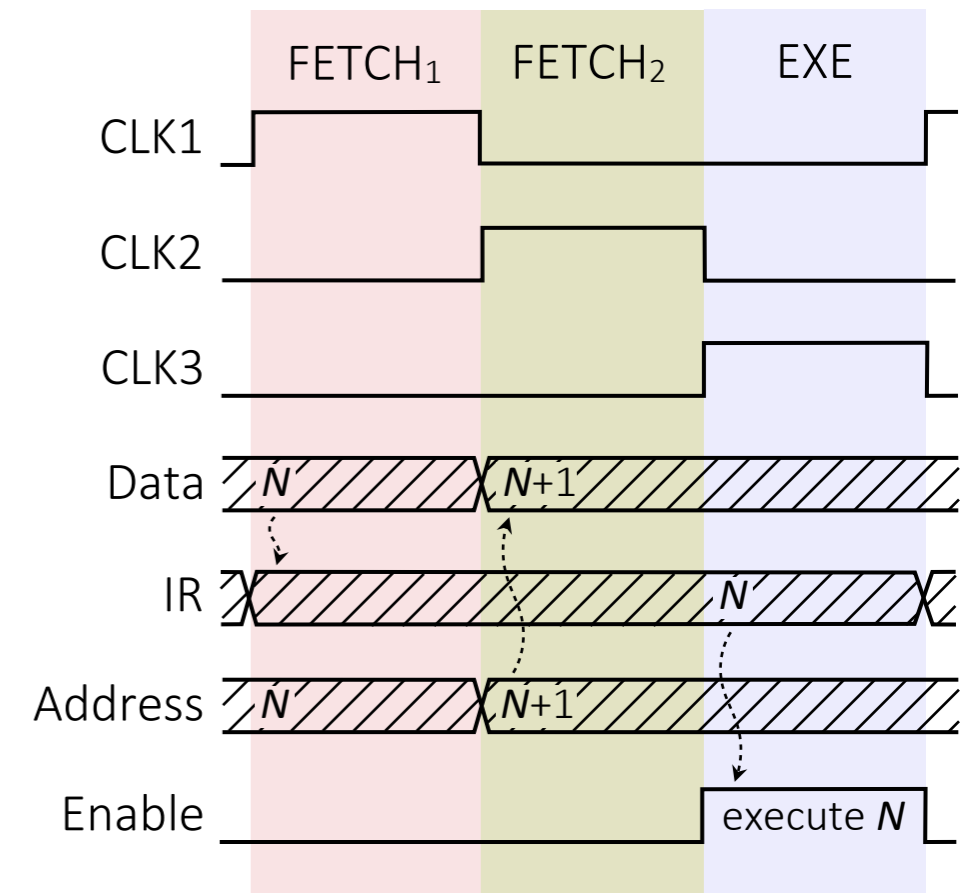
		Complexity	2D semiconductor-based circuits
SSI	Small-scale integration	1-10	State-of-the-art
MSI	Medium-scale integration	10-100	↓
LSI	Large-scale integration	100-100.000	
VLSI	Very large-scale integration	>100.000	

\*Computer Networks (A.S. Tanenbaum)

# MoS<sub>2</sub> microprocessor architecture



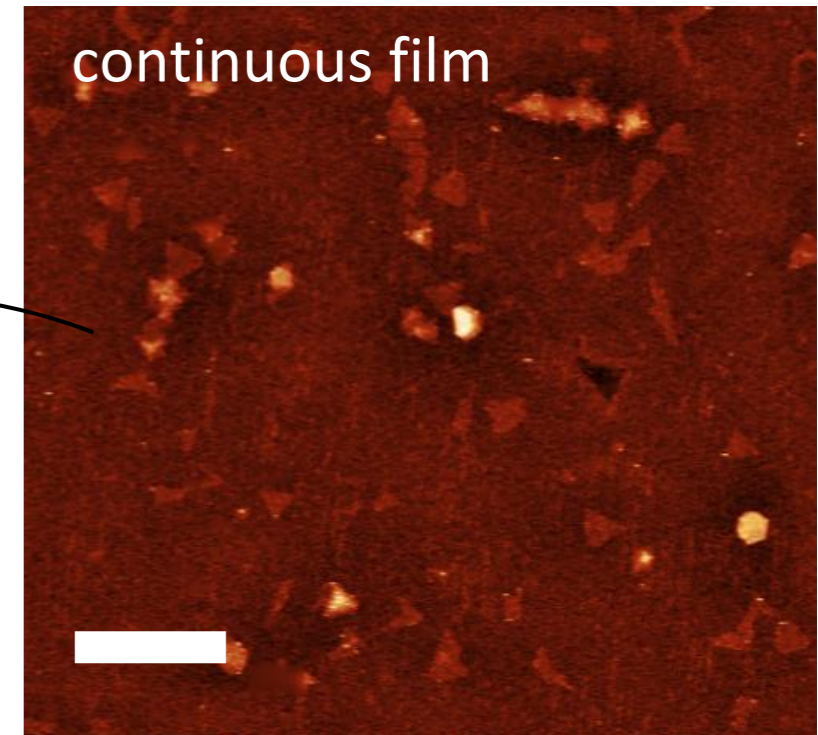
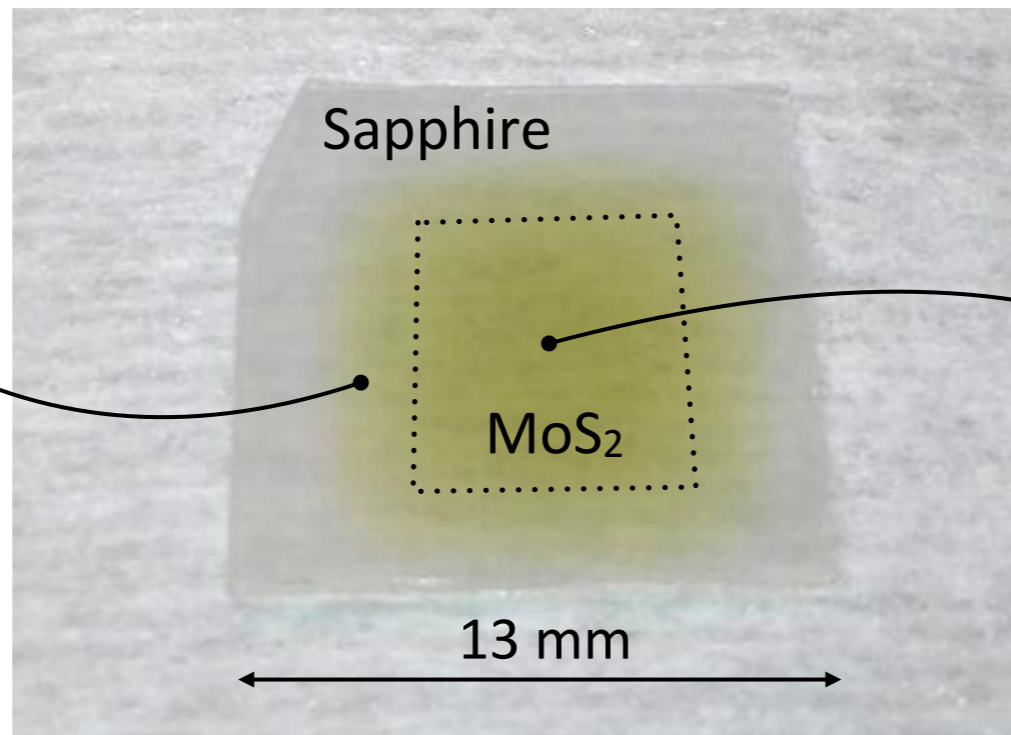
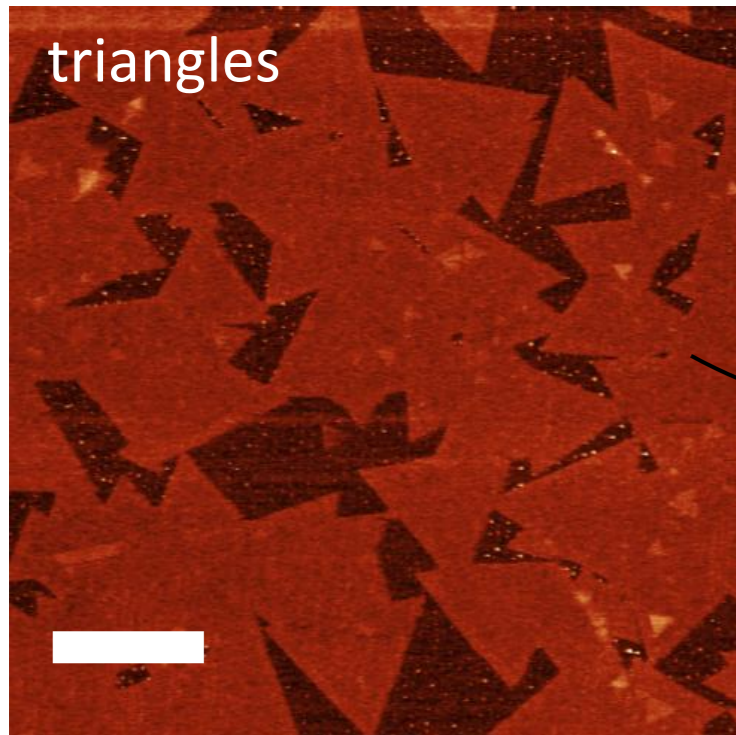
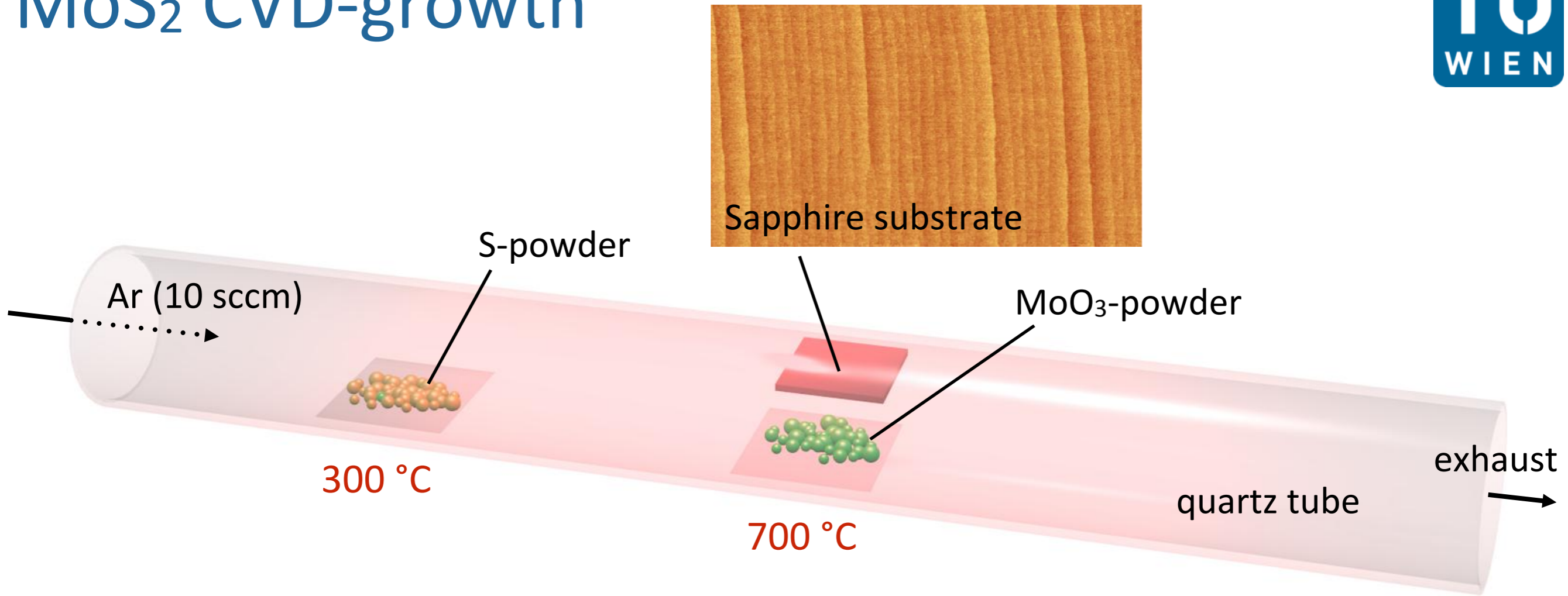
## Timing diagram:



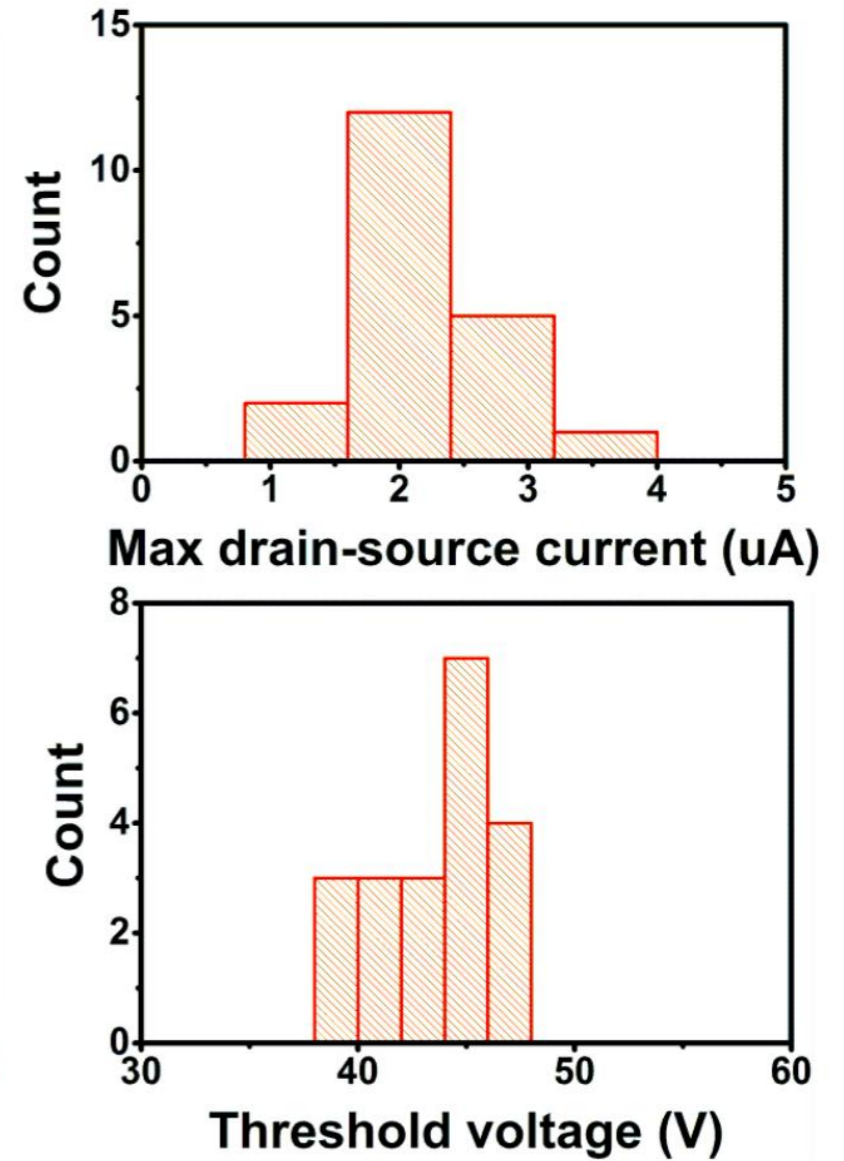
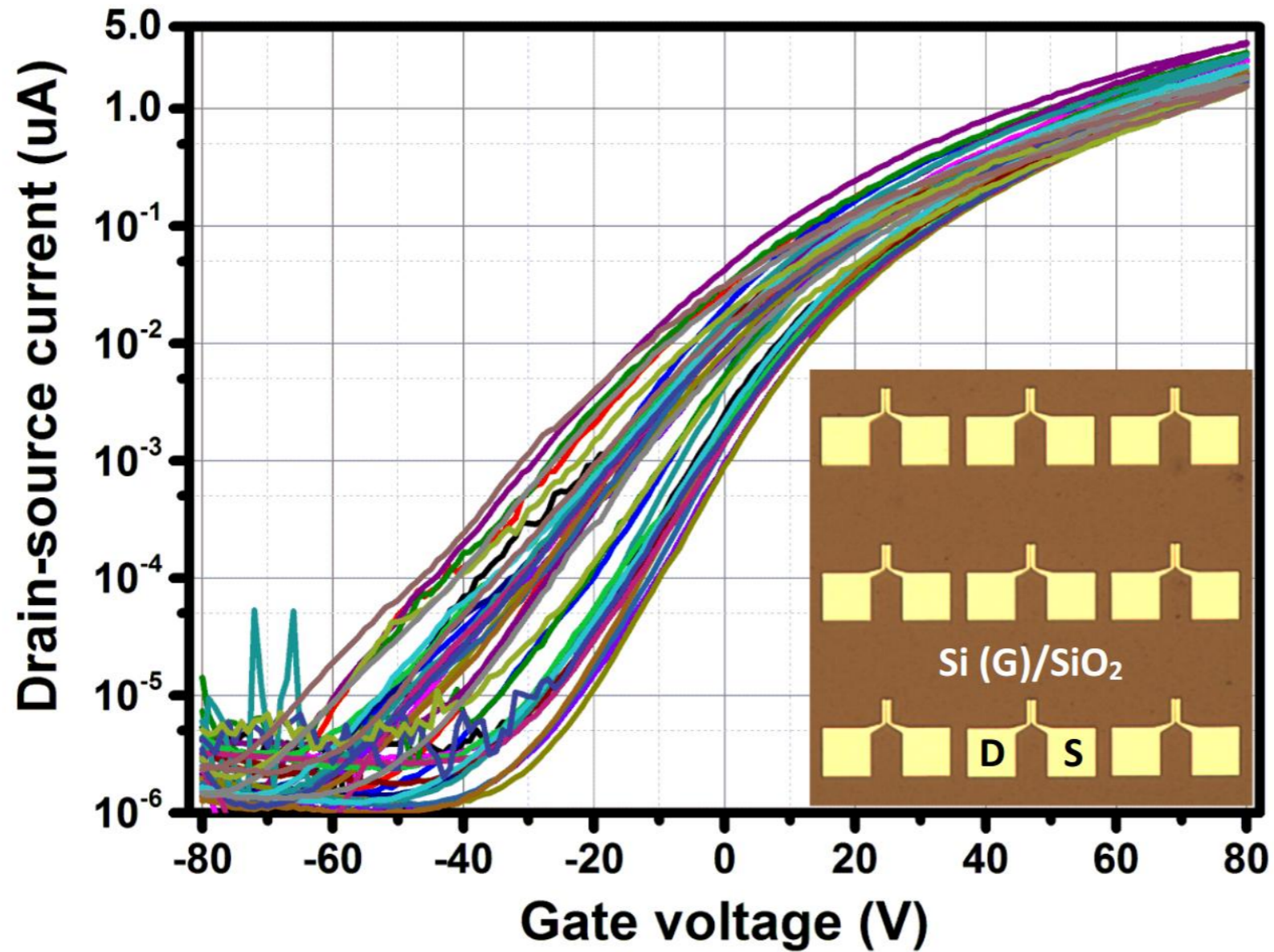
## Instruction set:

Command	Code	Example
NOP	00	NOP
LDA	01	LDA 0
AND	10	AND 1
OR	11	OR 0

# MoS<sub>2</sub> CVD-growth

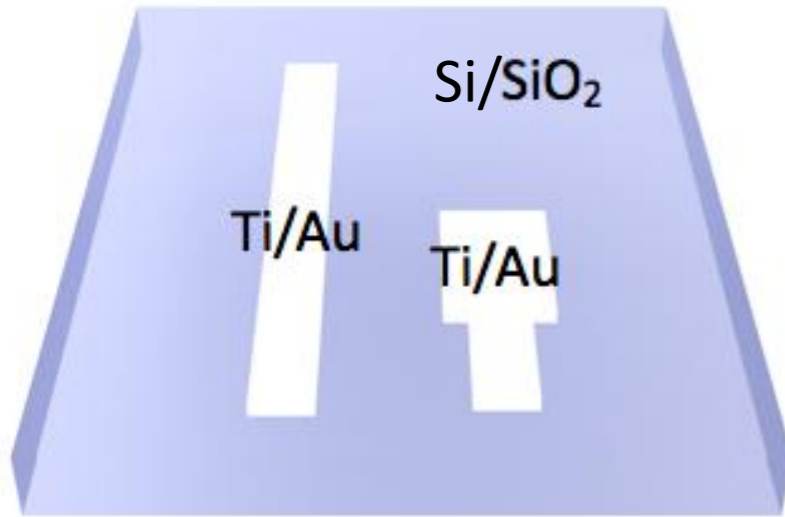


# MoS<sub>2</sub> film uniformity

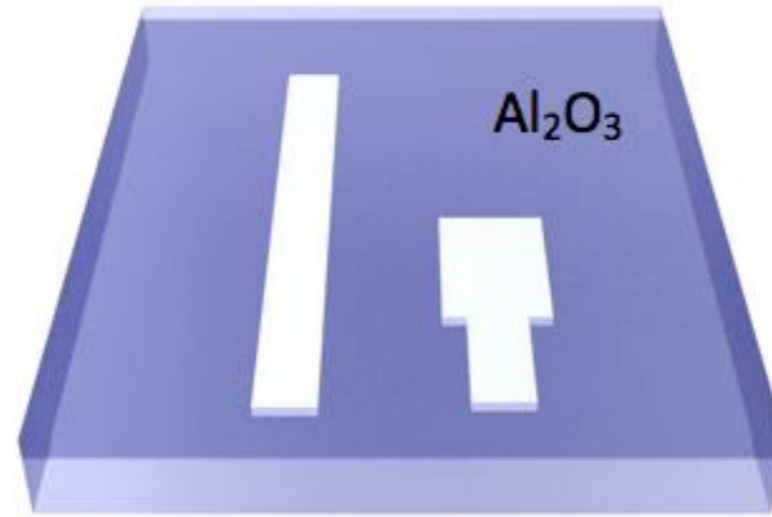


# Gate-first technology

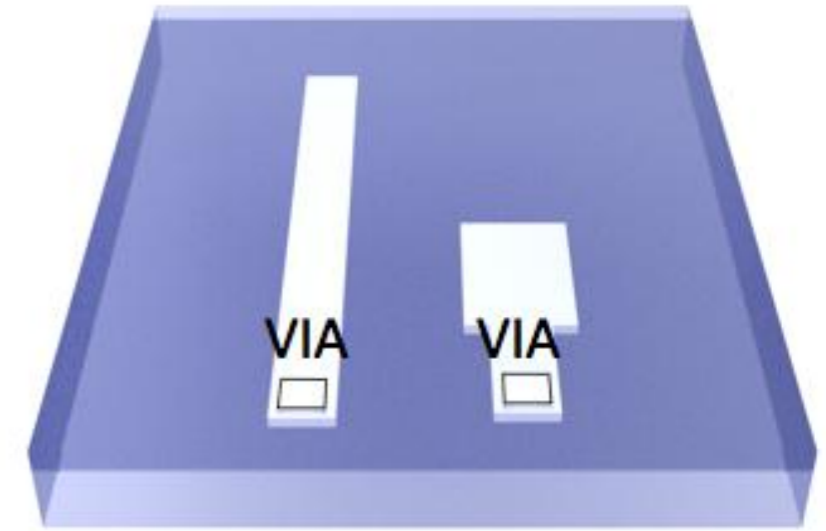
1. Bottom metal deposition



2. Gate dielectric deposition



3. Via-hole etching



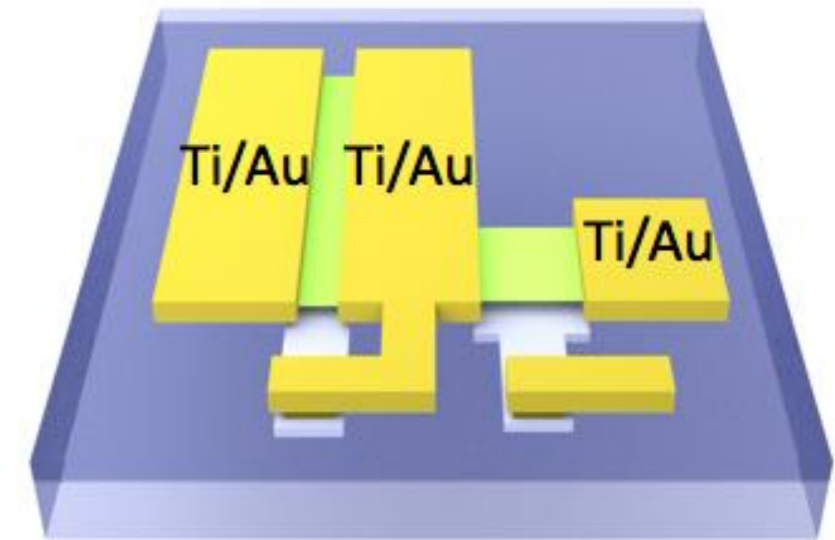
4. MoS<sub>2</sub> transfer



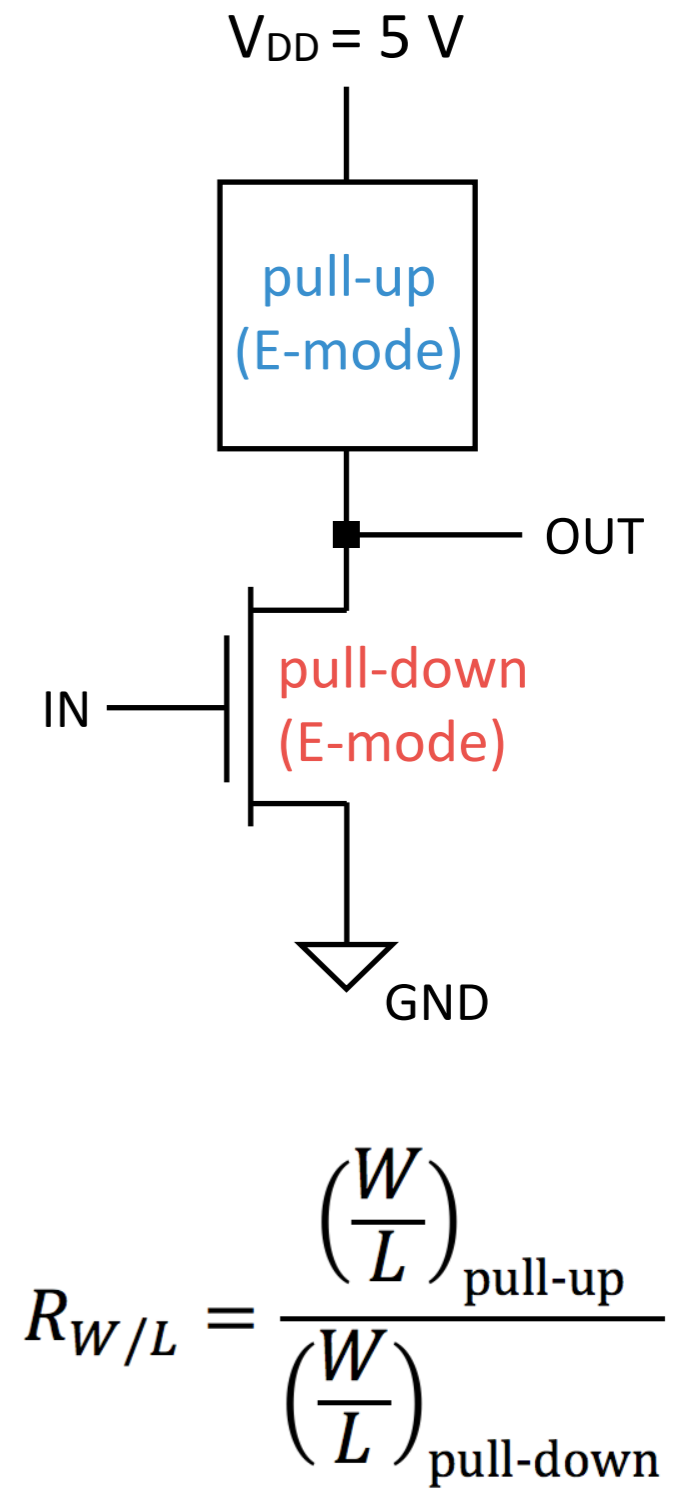
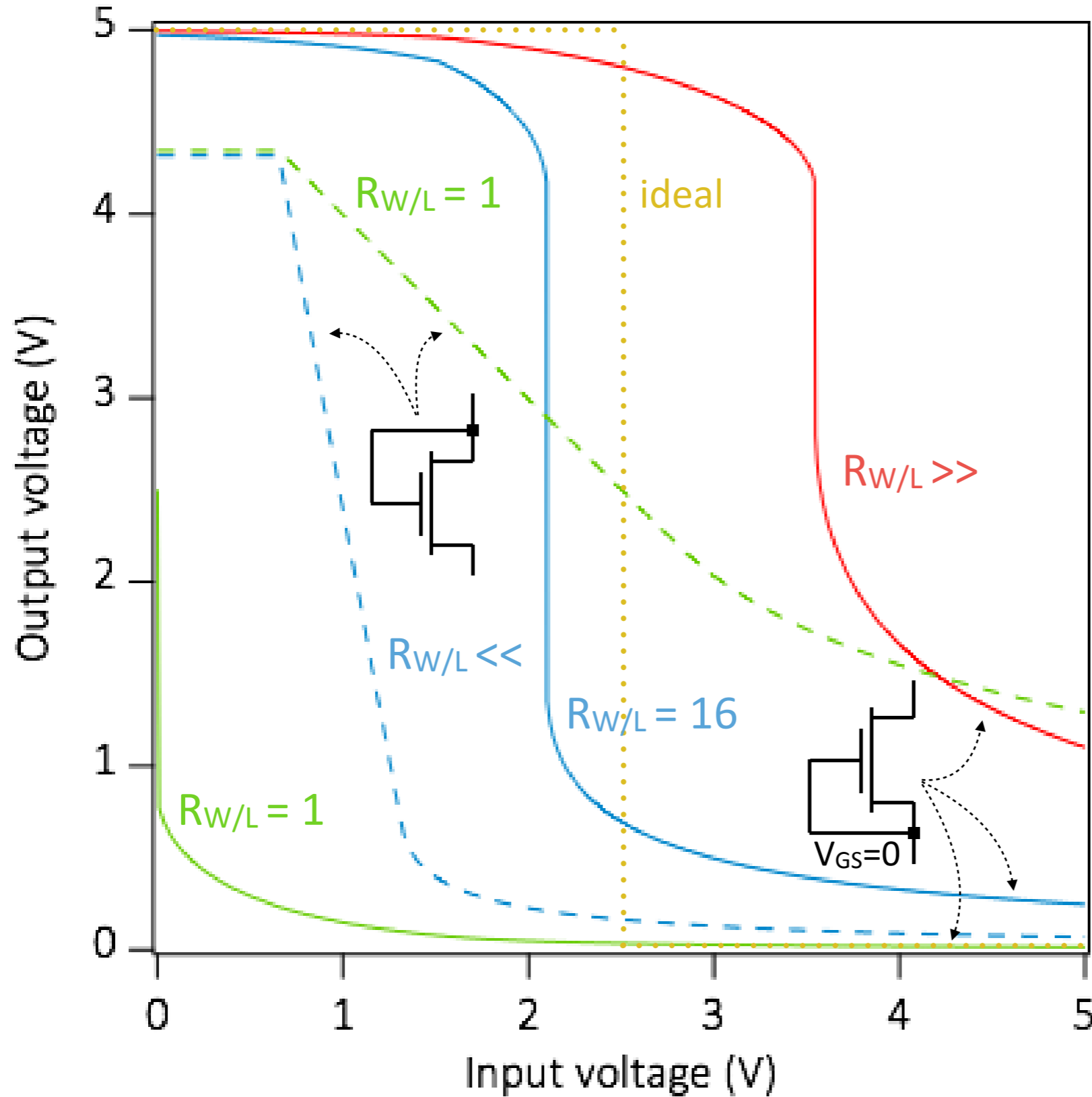
5. MoS<sub>2</sub> etching



6. Top metal deposition

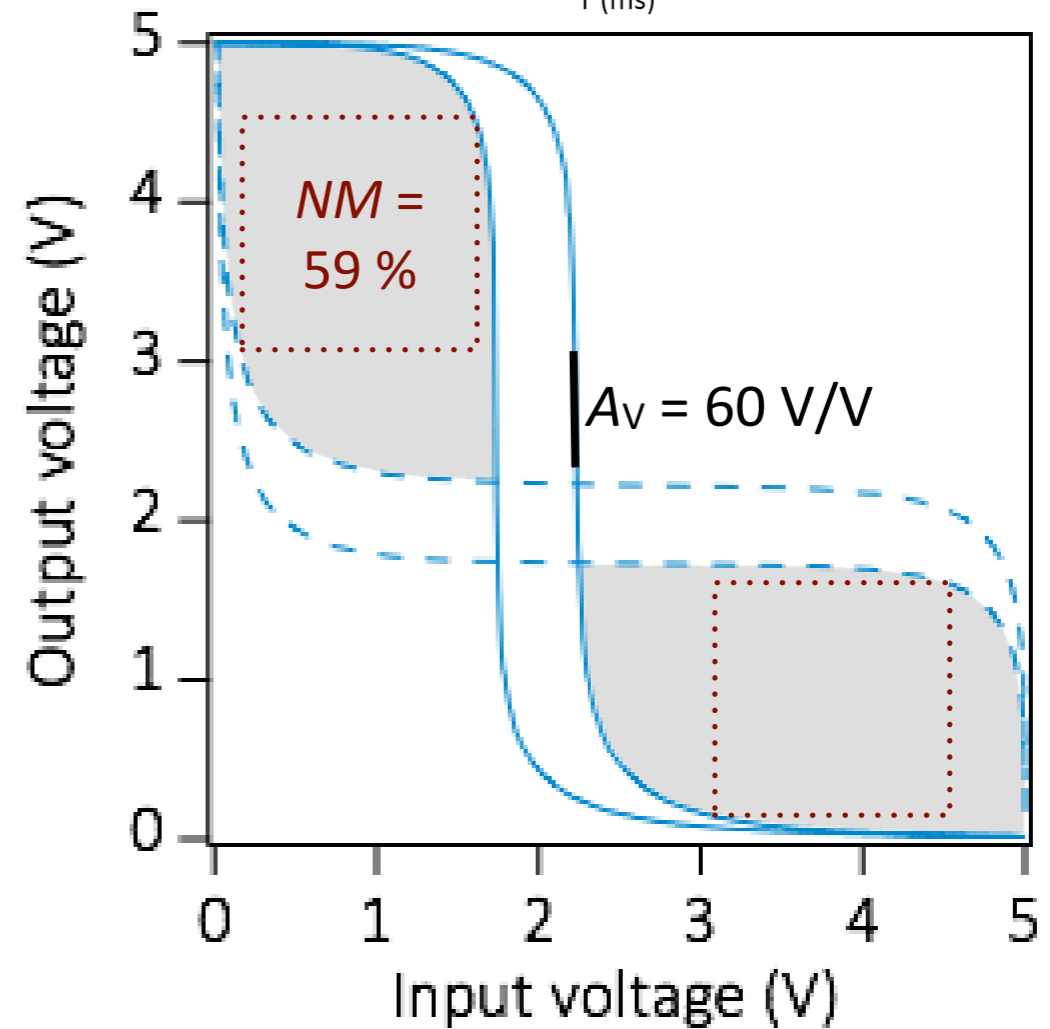
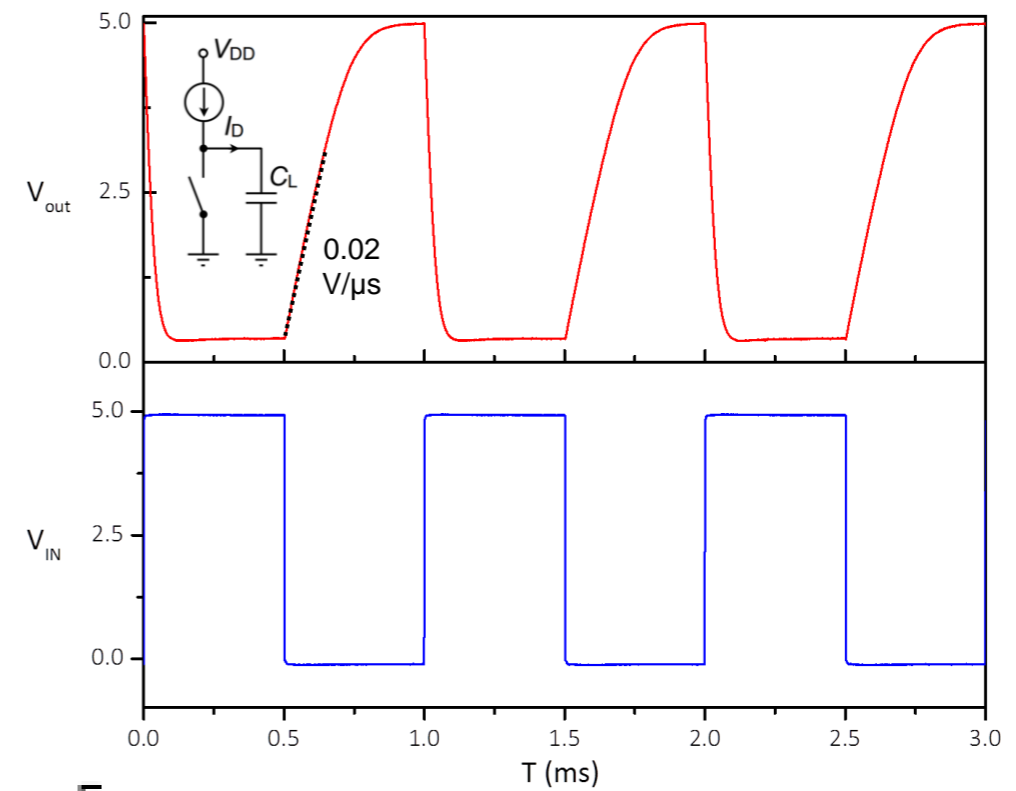
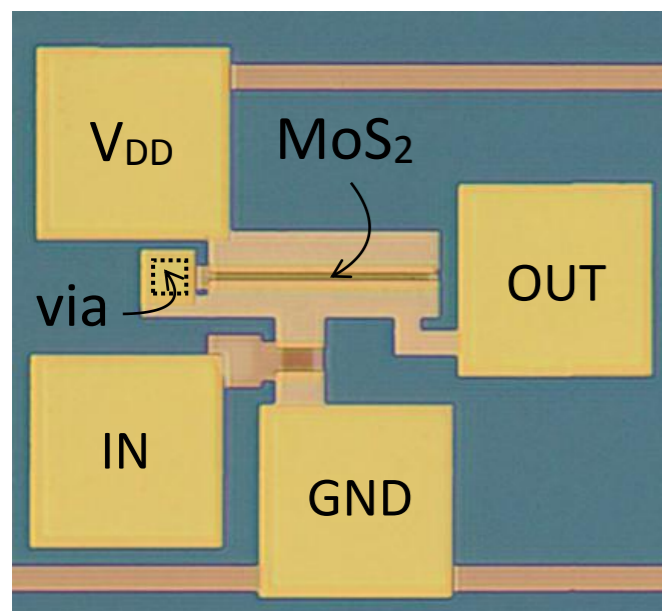
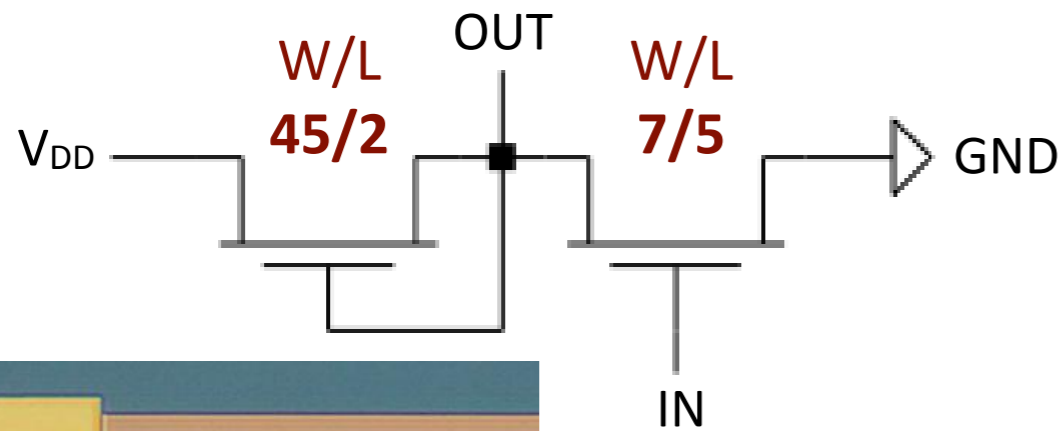
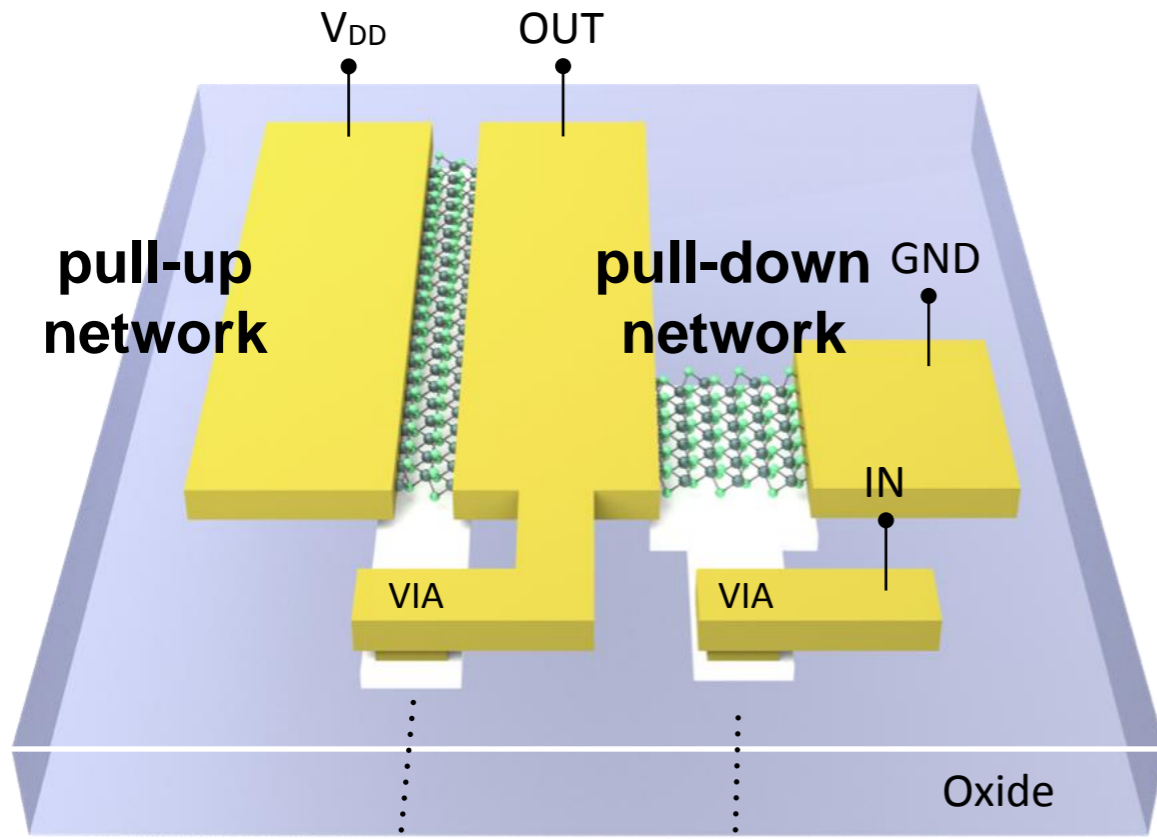


# NMOS logic



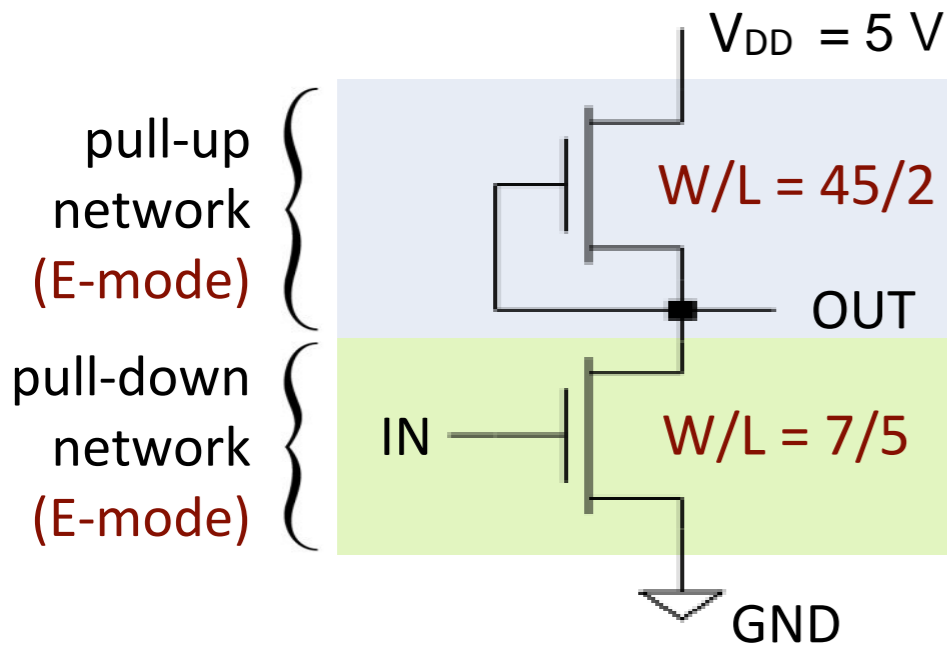


# NMOS inverter

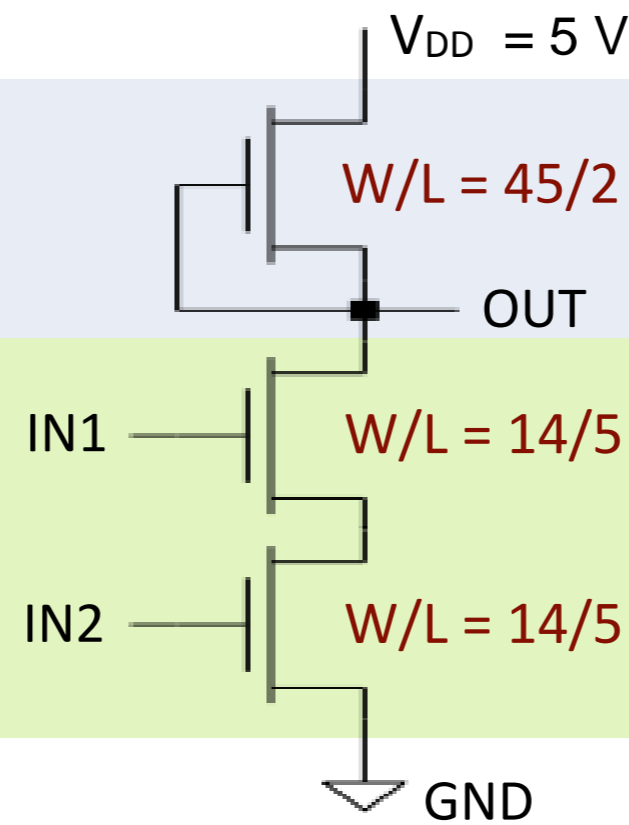


# NMOS logic stages

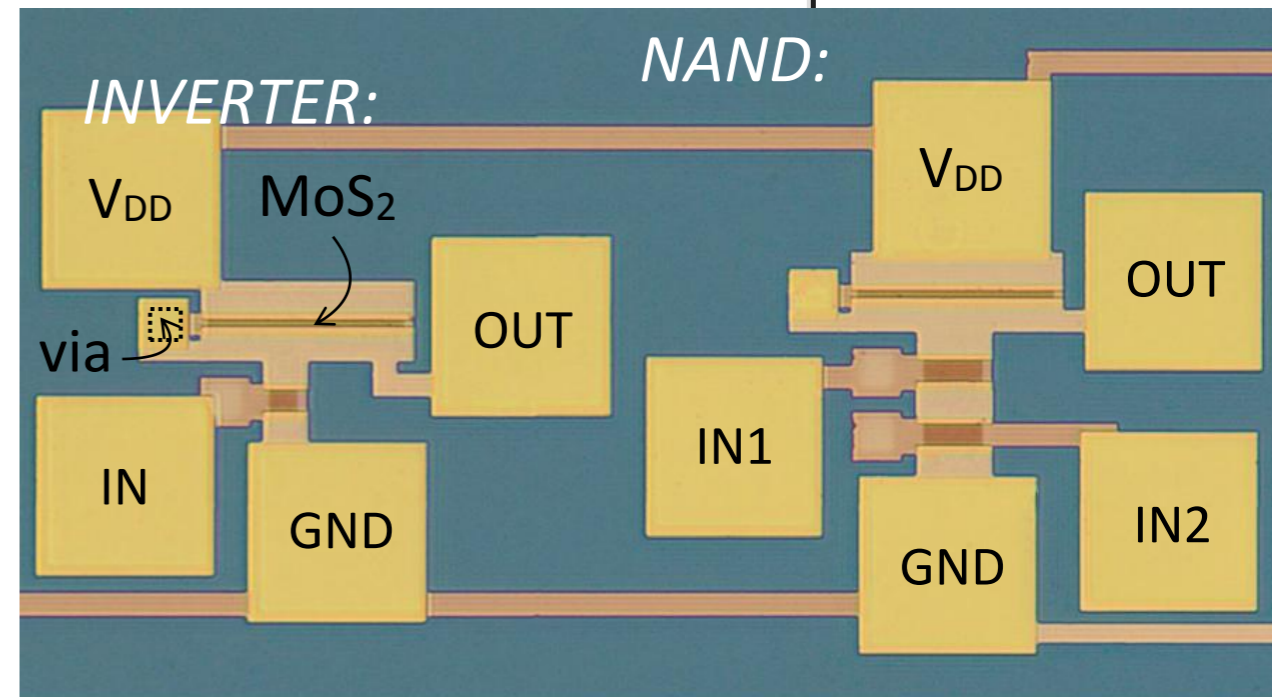
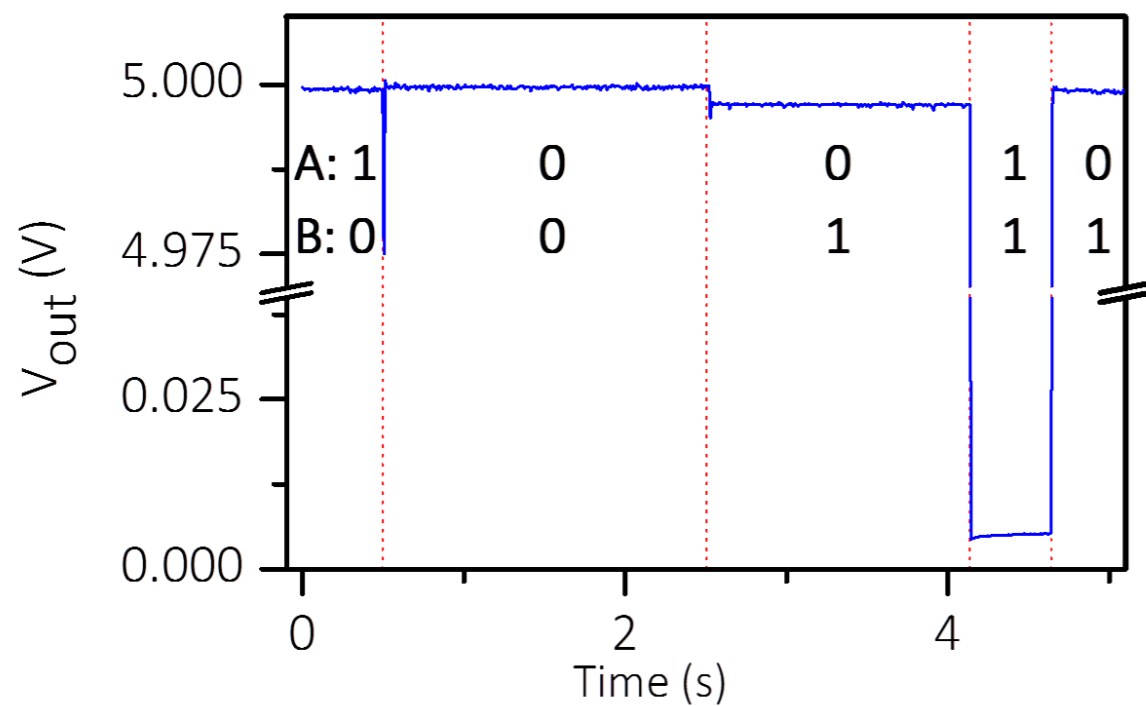
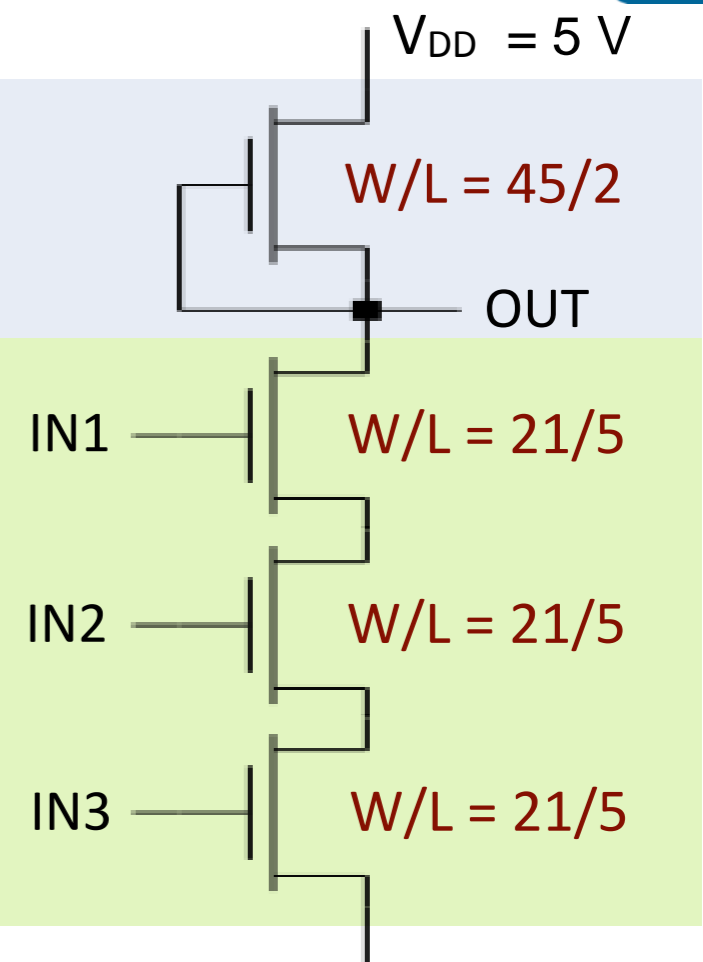
**INVERTER:**



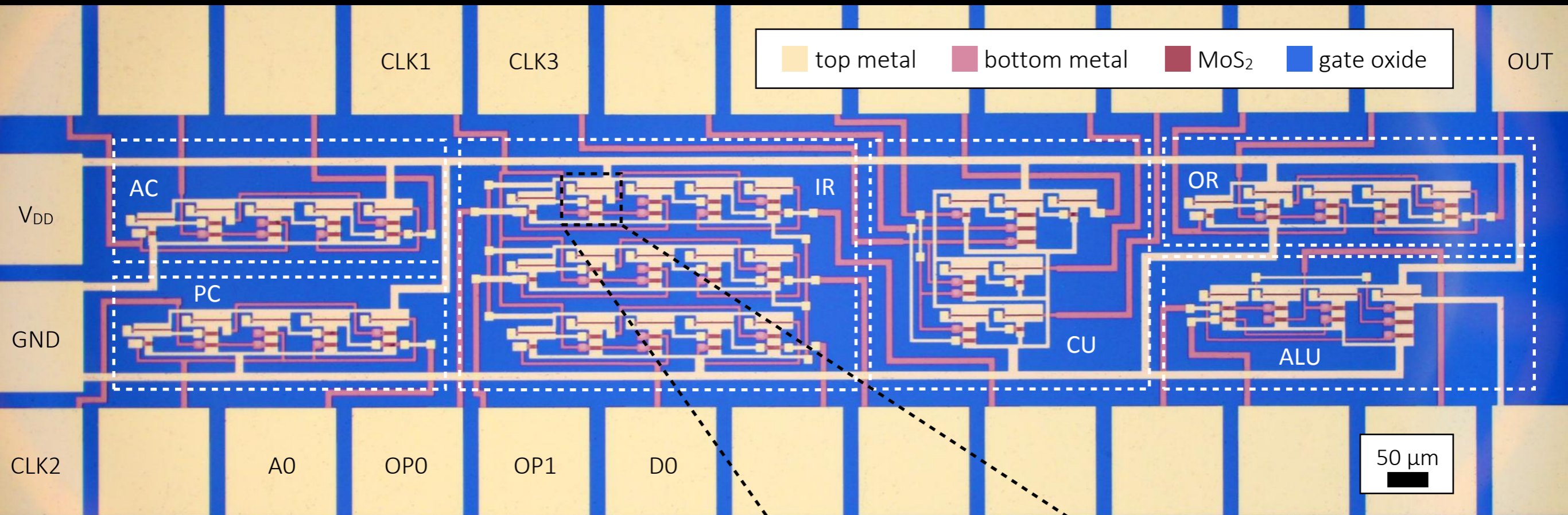
**2-NAND:**



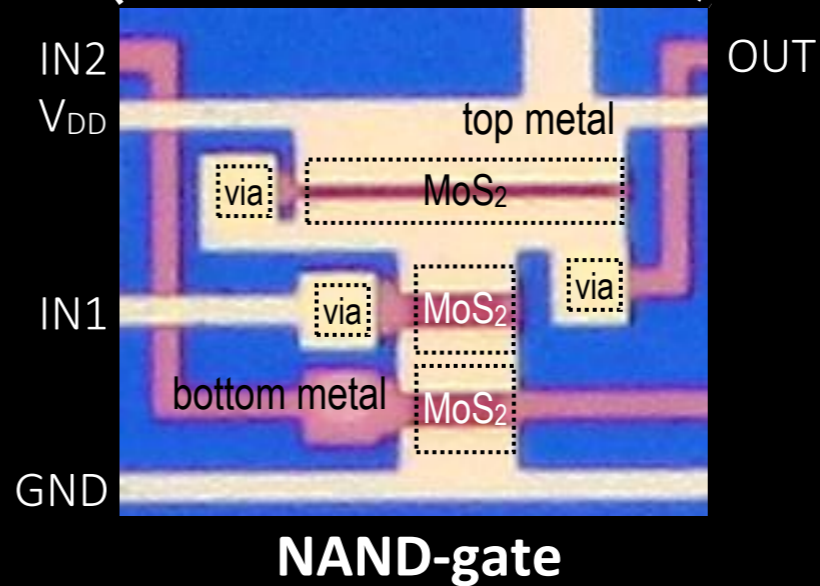
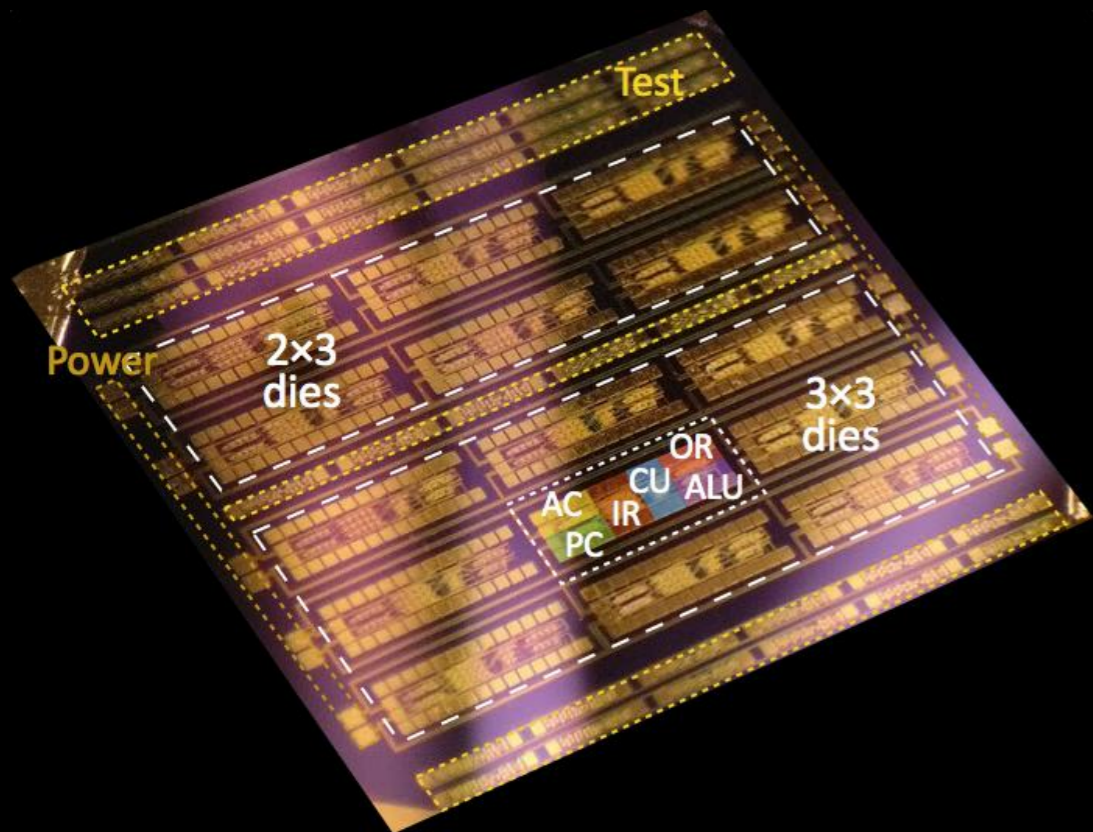
**3-NAND:**



# MoS<sub>2</sub> microprocessor



TO EXTERNAL MEMORY



115 transistors  
 $A = 0.6 \text{ mm}^2$   
 $P_s = 60 \text{ } \mu\text{W}$

NAND-gate

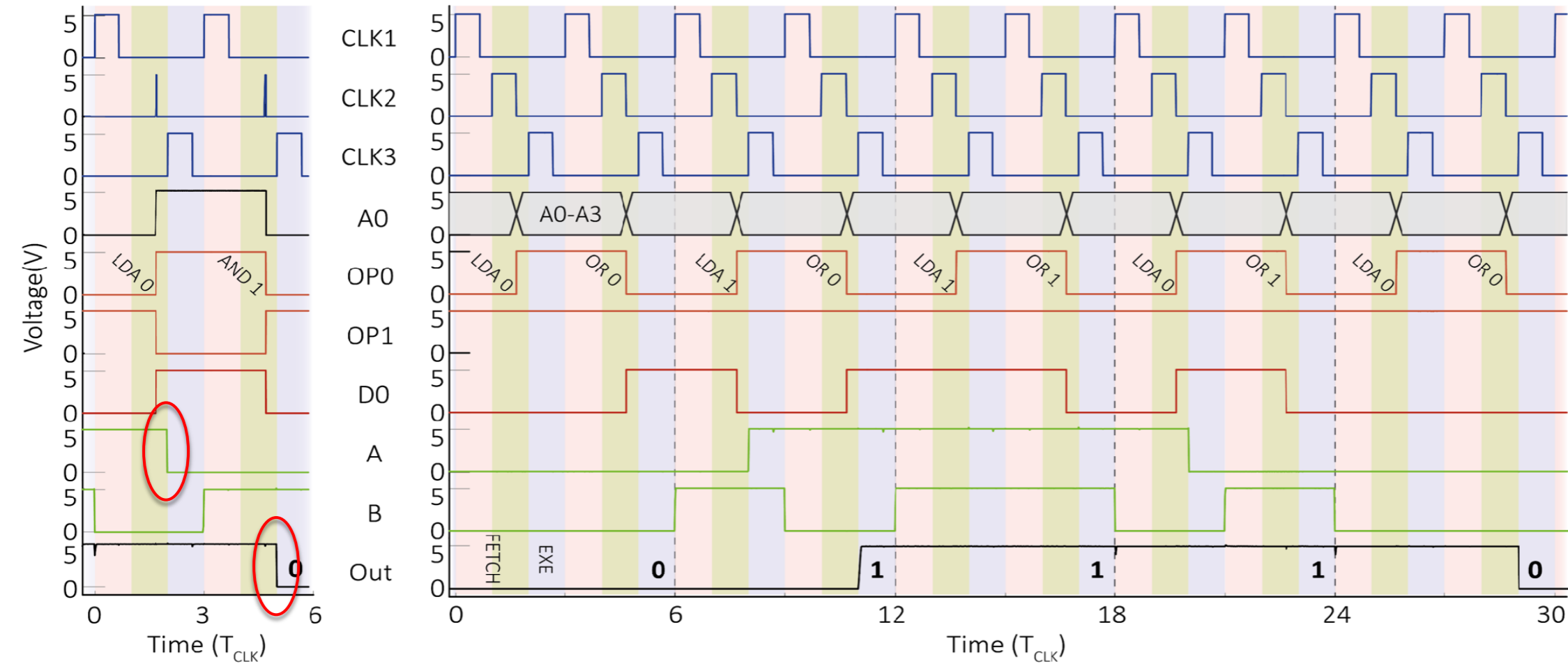
# Device operation

## Example 1:

LDA 0

AND 1

## Example 2: series of logical disjunction operations

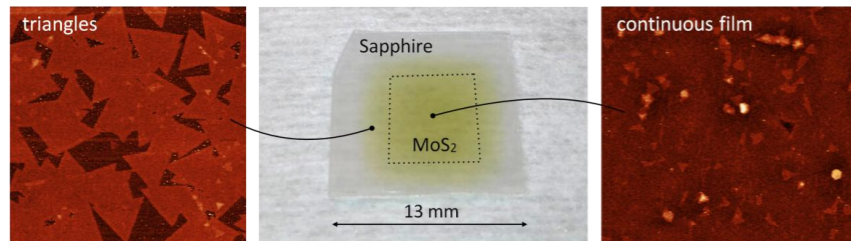


## challenges:

- device uniformity
- contact resistance
- CMOS...

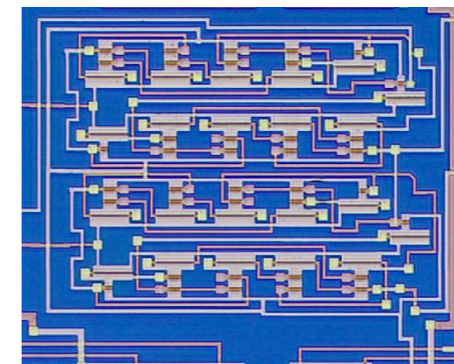
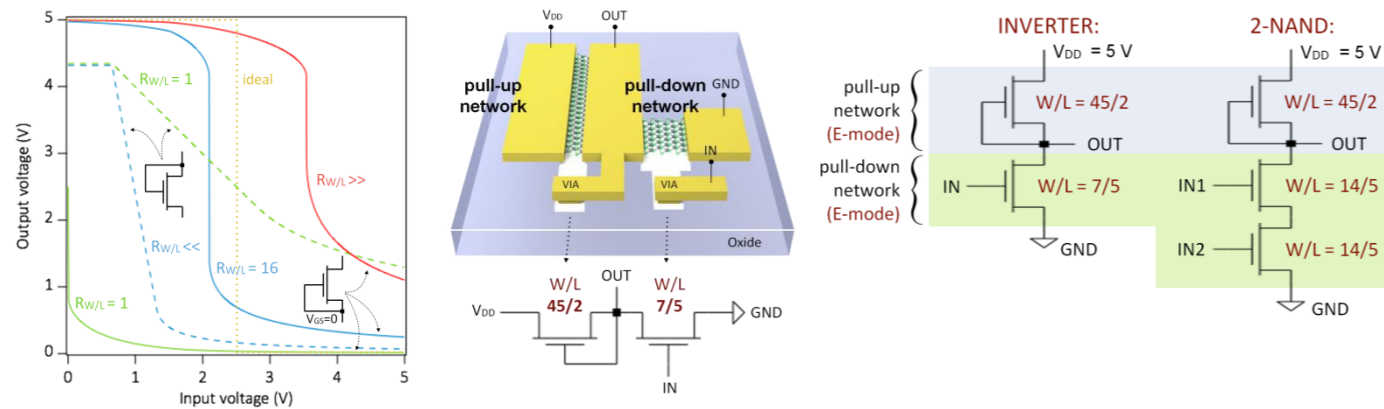
# Summary

## cm-scale uniform MoS<sub>2</sub> film growth



## W/L ratio designed MoS<sub>2</sub> logic gates

→ Cascadable



## large, complex circuits → microprocessor

